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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	11
Program Memory Size	7KB (4K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	14-SOIC (0.154", 3.90mm Width)
Supplier Device Package	14-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f1824-e-sl

3.2.1.1 STATUS Register

The STATUS register, shown in Register 3-1, contains:

- the arithmetic status of the ALU
- the Reset status

The STATUS register can be the destination for any instruction, like any other register. If the STATUS register is the destination for an instruction that affects the Z, DC or C bits, then the write to these three bits is disabled. These bits are set or cleared according to the device logic. Furthermore, the $\overline{TO}$ and $\overline{PD}$ bits are not writable. Therefore, the result of an instruction with the STATUS register as destination may be different than intended.

For example, `CLRF STATUS` will clear the upper three bits and set the Z bit. This leaves the STATUS register as '`000u u1uu`' (where u = unchanged).

It is recommended, therefore, that only `BCF`, `BSF`, `SWAPF` and `MOVWF` instructions are used to alter the STATUS register, because these instructions do not affect any Status bits. For other instructions not affecting any Status bits (Refer to **Section 29.0 "Instruction Set Summary"**).

Note 1: The C and DC bits operate as $\overline{Borrow}$ and $\overline{Digit\ Borrow}$ out bits, respectively, in subtraction.

REGISTER 3-1: STATUS: STATUS REGISTER

U-0	U-0	U-0	R-1/q	R-1/q	R/W-0/u	R/W-0/u	R/W-0/u
—	—	—	$\overline{TO}$	$\overline{PD}$	Z	DC(1)	C(1)
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	q = Value depends on condition

bit 7-5 **Unimplemented:** Read as '0'

bit 4 **$\overline{TO}$:** Time-out bit
- 1 = After power-up, `CLRWDT` instruction or `SLEEP` instruction
- 0 = A WDT time-out occurred

bit 3 **$\overline{PD}$:** Power-down bit
- 1 = After power-up or by the `CLRWDT` instruction
- 0 = By execution of the `SLEEP` instruction

bit 2 **Z:** Zero bit
- 1 = The result of an arithmetic or logic operation is zero
- 0 = The result of an arithmetic or logic operation is not zero

bit 1 **DC:** Digit Carry/$\overline{Digit\ Borrow}$ bit (`ADDWF`, `ADDLW`, `SUBLW`, `SUBWF` instructions)(1)
- 1 = A carry-out from the 4th low-order bit of the result occurred
- 0 = No carry-out from the 4th low-order bit of the result

bit 0 **C:** Carry/$\overline{Borrow}$ bit (`ADDWF`, `ADDLW`, `SUBLW`, `SUBWF` instructions)(1)
- 1 = A carry-out from the Most Significant bit of the result occurred
- 0 = No carry-out from the Most Significant bit of the result occurred

Note 1: For $\overline{Borrow}$, the polarity is reversed. A subtraction is executed by adding the two's complement of the second operand. For rotate (`RRF`, `RLF`) instructions, this bit is loaded with either the high-order or low-order bit of the source register.

TABLE 3-9: SPECIAL FUNCTION REGISTER SUMMARY (CONTINUED)

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
Bank 4											
200h(1)	INDF0	Addressing this location uses contents of FSR0H/FSR0L to address data memory (not a physical register)								xxxx xxxx	xxxx xxxx
201h(1)	INDF1	Addressing this location uses contents of FSR1H/FSR1L to address data memory (not a physical register)								xxxx xxxx	xxxx xxxx
202h(1)	PCL	Program Counter (PC) Least Significant Byte								0000 0000	0000 0000
203h(1)	STATUS	—	—	—	$\overline{TO}$	$\overline{PD}$	Z	DC	C	---1 1000	---q quuu
204h(1)	FSR0L	Indirect Data Memory Address 0 Low Pointer								0000 0000	uuuu uuuu
205h(1)	FSR0H	Indirect Data Memory Address 0 High Pointer								0000 0000	0000 0000
206h(1)	FSR1L	Indirect Data Memory Address 1 Low Pointer								0000 0000	uuuu uuuu
207h(1)	FSR1H	Indirect Data Memory Address 1 High Pointer								0000 0000	0000 0000
208h(1)	BSR	—	—	—	BSR<4:0>					---0 0000	---0 0000
209h(1)	WREG	Working Register								0000 0000	uuuu uuuu
20Ah(1)	PCLATH	—	Write Buffer for the upper 7 bits of the Program Counter							-000 0000	-000 0000
20Bh(1)	INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	0000 000x	0000 000u
20Ch	WPUA	—	—	WPUA5	WPUA4	WPUA3	WPUA2	WPUA1	WPUA0	--11 1111	--11 1111
20Dh	WPUB(2)	WPUB7	WPUB6	WPUB5	WPUB4	—	—	—	—	1111 ----	1111 ----
20Eh	WPUC	WPUC7(2)	WPUC6(2)	WPUC5	WPUC4	WPUC3	WPUC2	WPUC1	WPUC0	1111 1111	1111 1111
20Fh	—	Unimplemented								—	—
210h	—	Unimplemented								—	—
211h	SSP1BUF	Synchronous Serial Port Receive Buffer/Transmit Register								xxxx xxxx	uuuu uuuu
212h	SSP1ADD	ADD<7:0>								0000 0000	0000 0000
213h	SSP1MSK	MSK<7:0>								1111 1111	1111 1111
214h	SSP1STAT	SMP	CKE	D/$\overline{A}$	P	S	R/$\overline{W}$	UA	BF	0000 0000	0000 0000
215h	SSP1CON1	WCOL	SSPOV	SSPEN	CKP	SSPM<3:0>				0000 0000	0000 0000
216h	SSP1CON2	GCEN	ACKSTAT	ACKDT	ACKEN	RCEN	PEN	RSEN	SEN	0000 0000	0000 0000
217h	SSP1CON3	ACKTIM	PCIE	SCIE	BOEN	SDAHT	SBCDE	AHEN	DHEN	0000 0000	0000 0000
218h	—	Unimplemented								—	—
219h	—	Unimplemented								—	—
21Ah	—	Unimplemented								—	—
21Bh	—	Unimplemented								—	—
21Ch	—	Unimplemented								—	—
21Dh	—	Unimplemented								—	—
21Eh	—	Unimplemented								—	—
21Fh	—	Unimplemented								—	—

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented, r = reserved.
Shaded locations are unimplemented, read as '0'.

Note 1: These registers can be addressed from any bank.
2: PIC16(L)F1828 only.
3: PIC16(L)F1824 only.
4: Unimplemented, read as '1'.

5.0 OSCILLATOR MODULE (WITH FAIL-SAFE CLOCK MONITOR)

5.1 Overview

The oscillator module has a wide variety of clock sources and selection features that allow it to be used in a wide range of applications while maximizing performance and minimizing power consumption. Figure 5-1 illustrates a block diagram of the oscillator module.

Clock sources can be supplied from external oscillators, quartz crystal resonators, ceramic resonators and Resistor-Capacitor (RC) circuits. In addition, the system clock source can be supplied from one of two internal oscillators and PLL circuits, with a choice of speeds selectable via software. Additional clock features include:

- Selectable system clock source between external or internal sources via software.
- Two-Speed Start-up mode, which minimizes latency between external oscillator start-up and code execution.
- Fail-Safe Clock Monitor (FSCM) designed to detect a failure of the external clock source (LP, XT, HS, EC or RC modes) and switch automatically to the internal oscillator.
- Oscillator Start-up Timer (OST) ensures stability of crystal oscillator sources

The oscillator module can be configured in one of eight clock modes.

1. ECL – External Clock Low-Power mode (0 MHz to 0.5 MHz)
2. ECM – External Clock Medium-Power mode (0.5 MHz to 4 MHz)
3. ECH – External Clock High-Power mode (4 MHz to 32 MHz)
4. LP – 32 kHz Low-Power Crystal mode.
5. XT – Medium Gain Crystal or Ceramic Resonator Oscillator mode (up to 4 MHz)
6. HS – High Gain Crystal or Ceramic Resonator mode (4 MHz to 20 MHz)
7. RC – External Resistor-Capacitor (RC).
8. INTOSC – Internal oscillator (31 kHz to 32 MHz).

Clock Source modes are selected by the FOSC<2:0> bits in the Configuration Word 1. The FOSC bits determine the type of oscillator that will be used when the device is first powered.

The EC clock mode relies on an external logic level signal as the device clock source. The LP, XT, and HS clock modes require an external crystal or resonator to be connected to the device. Each mode is optimized for a different frequency range. The RC clock mode requires an external resistor and capacitor to set the oscillator frequency.

The INTOSC internal oscillator block produces low, medium, and high frequency clock sources, designated LFINTOSC, MFINTOSC, and HFINTOSC. (see Internal Oscillator Block, Figure 5-1). A wide selection of device clock frequencies may be derived from these three clock sources.

5.2.2.7 Internal Oscillator Clock Switch Timing

When switching between the HFINTOSC, MFINTOSC and the LFINTOSC, the new oscillator may already be shut down to save power (see Figure 5-7). If this is the case, there is a delay after the IRCF<3:0> bits of the OSCCON register are modified before the frequency selection takes place. The OSCSTAT register will reflect the current active status of the HFINTOSC, MFINTOSC and LFINTOSC oscillators. The sequence of a frequency selection is as follows:

1. IRCF<3:0> bits of the OSCCON register are modified.
2. If the new clock is shut down, a clock start-up delay is started.
3. Clock switch circuitry waits for a falling edge of the current clock.
4. The current clock is held low and the clock switch circuitry waits for a rising edge in the new clock.
5. The new clock is now active.
6. The OSCSTAT register is updated as required.
7. Clock switch is complete.

See Figure 5-7 for more details.

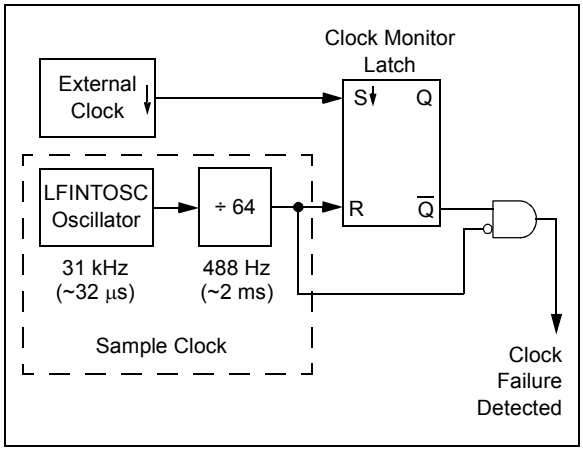
If the internal oscillator speed is switched between two clocks of the same source, there is no start-up delay before the new frequency is selected. Clock switching time delays are shown in Table 5-1.

Start-up delay specifications are located in the oscillator tables of **Section 30.0 "Electrical Specifications"**.

5.5 Fail-Safe Clock Monitor

The Fail-Safe Clock Monitor (FSCM) allows the device to continue operating should the external oscillator fail. The FSCM can detect oscillator failure any time after the Oscillator Start-up Timer (OST) has expired. The FSCM is enabled by setting the FCMEN bit in the Configuration Word 1. The FSCM is applicable to all external Oscillator modes (LP, XT, HS, EC, Timer1 Oscillator and RC).

FIGURE 5-9: FSCM BLOCK DIAGRAM



5.5.1 FAIL-SAFE DETECTION

The FSCM module detects a failed oscillator by comparing the external oscillator to the FSCM sample clock. The sample clock is generated by dividing the LFINTOSC by 64. See Figure 5-9. Inside the fail detector block is a latch. The external clock sets the latch on each falling edge of the external clock. The sample clock clears the latch on each rising edge of the sample clock. A failure is detected when an entire half-cycle of the sample clock elapses before the external clock goes low.

5.5.2 FAIL-SAFE OPERATION

When the external clock fails, the FSCM switches the device clock to an internal clock source and sets the bit flag OSFIF of the PIR2 register. Setting this flag will generate an interrupt if the OSFIE bit of the PIE2 register is also set. The device firmware can then take steps to mitigate the problems that may arise from a failed clock. The system clock will continue to be sourced from the internal clock source until the device firmware successfully restarts the external oscillator and switches back to external operation.

The internal clock source chosen by the FSCM is determined by the IRCF<3:0> bits of the OSCCON register. This allows the internal oscillator to be configured before a failure occurs.

5.5.3 FAIL-SAFE CONDITION CLEARING

The Fail-Safe condition is cleared after a Reset, executing a SLEEP instruction or changing the SCS bits of the OSCCON register. When the SCS bits are changed, the OST is restarted. While the OST is running, the device continues to operate from the INTOSC selected in OSCCON. When the OST times out, the Fail-Safe condition is cleared after successfully switching to the external clock source. The OSFIF bit should be cleared prior to switching to the external clock source. If the Fail-Safe condition still exists, the OSFIF flag will again become set by hardware.

5.5.4 RESET OR WAKE-UP FROM SLEEP

The FSCM is designed to detect an oscillator failure after the Oscillator Start-up Timer (OST) has expired. The OST is used after waking up from Sleep and after any type of Reset. The OST is not used with the EC or RC Clock modes so that the FSCM will be active as soon as the Reset or wake-up has completed. When the FSCM is enabled, the Two-Speed Start-up is also enabled. Therefore, the device will always be executing code while the OST is operating.

Note:	Due to the wide range of oscillator start-up times, the Fail-Safe circuit is not active during oscillator start-up (i.e., after exiting Reset or Sleep). After an appropriate amount of time, the user should check the Status bits in the OSCSTAT register to verify the oscillator start-up and that the system clock switchover has successfully completed.

7.1 Power-on Reset (POR)

The POR circuit holds the device in Reset until VDD has reached an acceptable level for minimum operation. Slow rising VDD, fast operating speeds or analog performance may require greater than minimum VDD. The PWRT, BOR or MCLR features can be used to extend the start-up period until all device operation conditions have been met.

7.1.1 POWER-UP TIMER (PWRT)

The Power-up Timer provides a nominal 64 ms time-out on POR or Brown-out Reset.

The device is held in Reset as long as PWRT is active. The PWRT delay allows additional time for the VDD to rise to an acceptable level. The Power-up Timer is enabled by clearing the PWRTE bit in Configuration Word 1.

The Power-up Timer starts after the release of the POR and BOR.

For additional information, refer to Application Note AN607, *"Power-up Trouble Shooting"* (DS00607).

7.2 Brown-Out Reset (BOR)

The BOR circuit holds the device in Reset when VDD reaches a selectable minimum level. Between the POR and BOR, complete voltage range coverage for execution protection can be implemented.

The Brown-out Reset module has four operating modes controlled by the BOREN<1:0> bits in Configuration Word 1. The four operating modes are:

- BOR is always on
- BOR is off when in Sleep
- BOR is controlled by software
- BOR is always off

Refer to Table 7-3 for more information.

The Brown-out Reset voltage level is selectable by configuring the BORV bit in Configuration Word 2.

A VDD noise rejection filter prevents the BOR from triggering on small events. If VDD falls below VBOR for a duration greater than parameter TBORDC, the device will reset. See Figure 7-3 for more information.

TABLE 7-1: BOR OPERATING MODES

BOREN Config bits	SBOREN	Device Mode	BOR Mode	Device Operation upon release of POR	Device Operation upon wake-up from Sleep
BOR_ON (11)	X	X	Active	Waits for BOR ready(1)	
BOR_NSLEEP (10)	X	Awake	Active	Waits for BOR ready	
BOR_NSLEEP (10)	X	Sleep	Disabled		
BOR_SBOREN (01)	1	X	Active	Begins immediately	
BOR_SBOREN (01)	0	X	Disabled	Begins immediately	
BOR_OFF (00)	X	X	Disabled	Begins immediately	

Note 1: In these specific cases, "Release of POR" and the "Wake-up from Sleep", there is no delay in start-up. The BOR Ready flag (BORRDY = 1) will be set before the CPU is ready to execute instructions because the BOR circuit is forced on by the BOREN<1:0> bits.

7.2.1 BOR IS ALWAYS ON

When the BOREN bits of Configuration Word 1 are set to '11', the BOR is always on. The device start-up will be delayed until the BOR is ready and VDD is higher than the BOR threshold.

BOR protection is active during Sleep. The BOR does not delay wake-up from Sleep.

7.2.2 BOR IS OFF IN SLEEP

When the BOREN bits of Configuration Word 1 are set to '10', the BOR is on, except in Sleep. The device start-up will be delayed until the BOR is ready and VDD is higher than the BOR threshold.

BOR protection is not active during Sleep. The device wake-up will be delayed until the BOR is ready.

7.2.3 BOR CONTROLLED BY SOFTWARE

When the BOREN bits of Configuration Word 1 are set to '01', the BOR is controlled by the SBOREN bit of the BORCON register. The device start-up is not delayed by the BOR ready condition or the VDD level.

BOR protection begins as soon as the BOR circuit is ready. The status of the BOR circuit is reflected in the BORRDY bit of the BORCON register.

BOR protection is unchanged by Sleep.

EXAMPLE 11-4: ERASING ONE ROW OF PROGRAM MEMORY

```
; This row erase routine assumes the following:
; 1. A valid address within the erase block is loaded in ADDRH:ADDRL
; 2. ADDRH and ADDRL are located in shared data memory 0x70 - 0x7F


        BCF         INTCON,GIE      ; Disable ints so required sequences will execute properly
        BANKSEL     EEADRL
        MOVF        ADDRL,W         ; Load lower 8 bits of erase address boundary
        MOVWF       EEADRL
        MOVF        ADDRH,W         ; Load upper 6 bits of erase address boundary
        MOVWF       EEADRH
        BSF         EECON1,EEPGD    ; Point to program memory
        BCF         EECON1,CFGS     ; Not configuration space
        BSF         EECON1,FREE     ; Specify an erase operation
        BSF         EECON1,WREN     ; Enable writes

Required
Sequence
        MOVLW       55h             ; Start of required sequence to initiate erase
        MOVWF       EECON2          ; Write 55h
        MOVLW       0AAh            ;
        MOVWF       EECON2          ; Write AAh
        BSF         EECON1,WR       ; Set WR bit to begin erase
        NOP                         ; Any instructions here are ignored as processor
                                    ; halts to begin erase sequence
        NOP                         ; Processor will stop here and wait for erase complete.

                                    ; after erase processor continues with 3rd instruction

        BCF         EECON1,WREN     ; Disable writes
        BSF         INTCON,GIE      ; Enable interrupts
```

TABLE 17-1: SUMMARY OF REGISTERS ASSOCIATED WITH THE DAC MODULE

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on page
FVRCON	FVREN	FVRRDY	TSEN	TSRNG	CDAFVR<1:0>		ADFVR<1:0>		141
DACCON0	DACEN	DACLPS	DACOE	—	DACPSS<1:0>		—	DACNSS	159
DACCON1	—	—	—	DACR<4:0>					159

Legend: — = unimplemented, read as '0'. Shaded cells are unused by the DAC module.

22.1 Timer2/4/6 Operation

The clock input to the Timer2/4/6 modules is the system instruction clock (FOSC/4).

TMRx increments from 00h on each clock edge.

A 4-bit counter/prescaler on the clock input allows direct input, divide-by-4 and divide-by-16 prescale options. These options are selected by the prescaler control bits, TxCKPS<1:0> of the TxCON register. The value of TMRx is compared to that of the Period register, PRx, on each clock cycle. When the two values match, the comparator generates a match signal as the timer output. This signal also resets the value of TMRx to 00h on the next cycle and drives the output counter/postscaler (see **Section 22.2 "Timer2/4/6 Interrupt"**).

The TMRx and PRx registers are both directly readable and writable. The TMRx register is cleared on any device Reset, whereas the PRx register initializes to FFh. Both the prescaler and postscaler counters are cleared on the following events:

- a write to the TMRx register
- a write to the TxCON register
- Power-on Reset (POR)
- Brown-out Reset (BOR)
- $\overline{\text{MCLR}}$ Reset
- Watchdog Timer (WDT) Reset
- Stack Overflow Reset
- Stack Underflow Reset
- RESET Instruction

Note:	TMRx is not cleared when TxCON is written.

22.2 Timer2/4/6 Interrupt

Timer2/4/6 can also generate an optional device interrupt. The Timer2/4/6 output signal (TMRx-to-PRx match) provides the input for the 4-bit counter/postscaler. This counter generates the TMRx match interrupt flag which is latched in TMRxIF of the PIRx register. The interrupt is enabled by setting the TMRx Match Interrupt Enable bit, TMRxIE of the PIEx register.

A range of 16 postscale options (from 1:1 through 1:16 inclusive) can be selected with the postscaler control bits, TxOUTPS<3:0>, of the TxCON register.

22.3 Timer2/4/6 Output

The unscaled output of TMRx is available primarily to the CCP modules, where it is used as a time base for operations in PWM mode.

Timer2 can be optionally used as the shift clock source for the MSSPx modules operating in SPI mode. Additional information is provided in **Section 25.1 "Master SSP (MSSP1) Module Overview"**.

22.4 Timer2/4/6 Operation During Sleep

The Timer2/4/6 timers cannot be operated while the processor is in Sleep mode. The contents of the TMRx and PRx registers will remain unchanged while the processor is in Sleep mode.

23.0 DATA SIGNAL MODULATOR

The Data Signal Modulator (DSM) is a peripheral which allows the user to mix a data stream, also known as a modulator signal, with a carrier signal to produce a modulated output.

Both the carrier and the modulator signals are supplied to the DSM module either internally, from the output of a peripheral, or externally through an input pin.

The modulated output signal is generated by performing a logical “AND” operation of both the carrier and modulator signals and then provided to the MDOUT pin.

The carrier signal is comprised of two distinct and separate signals. A carrier high (CARH) signal and a carrier low (CARL) signal. During the time in which the modulator (MOD) signal is in a logic high state, the DSM mixes the carrier high signal with the modulator signal. When the modulator signal is in a logic low state, the DSM mixes the carrier low signal with the modulator signal.

Using this method, the DSM can generate the following types of key modulation schemes:

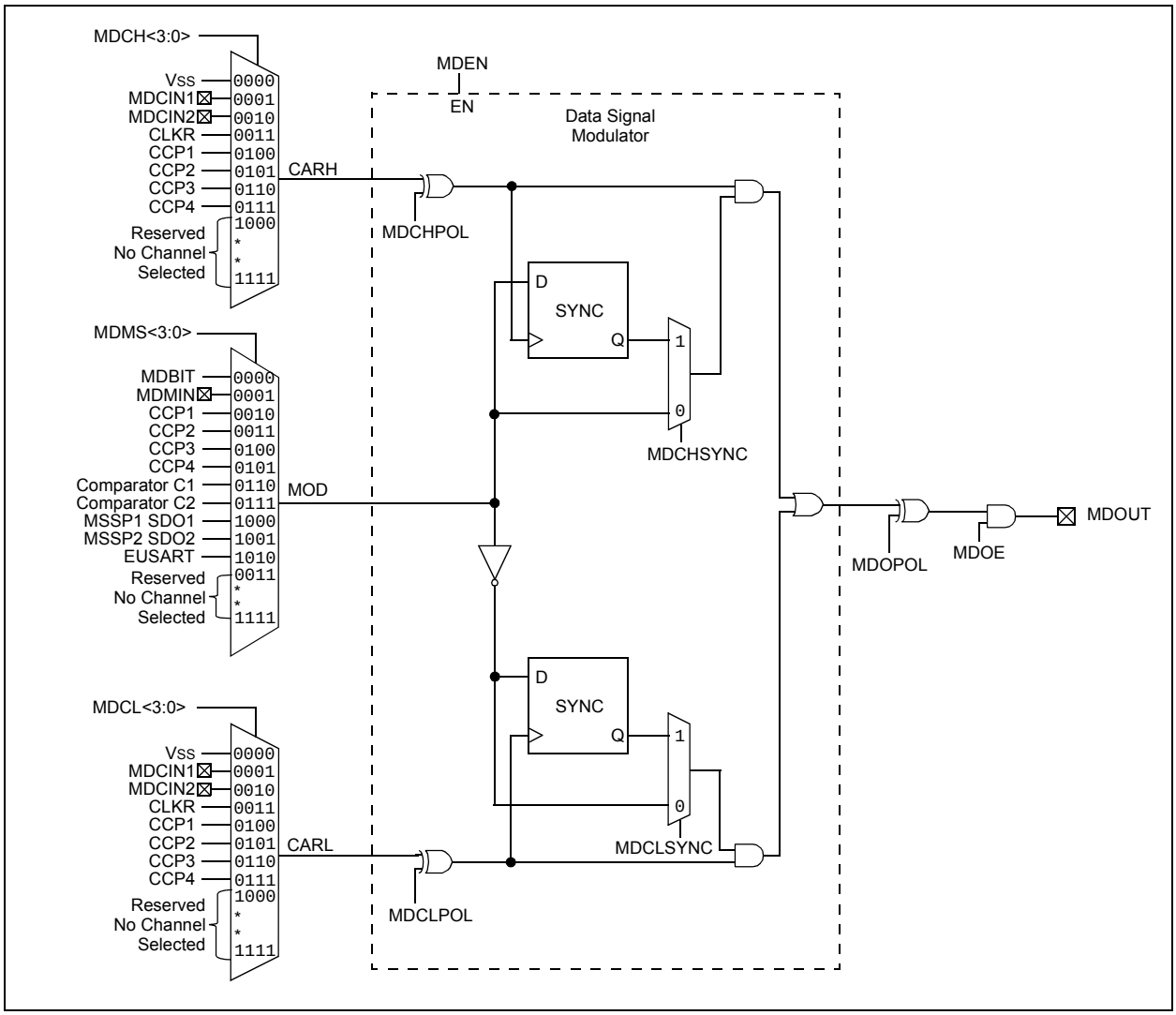
- Frequency-Shift Keying (FSK)
- Phase-Shift Keying (PSK)
- On-Off Keying (OOK)

Additionally, the following features are provided within the DSM module:

- Carrier Synchronization
- Carrier Source Polarity Select
- Carrier Source Pin Disable
- Programmable Modulator Data
- Modulator Source Pin Disable
- Modulated Output Polarity Select
- Slew Rate Control

Figure 23-1 shows a Simplified Block Diagram of the Data Signal Modulator peripheral.

FIGURE 23-1: SIMPLIFIED BLOCK DIAGRAM OF THE DATA SIGNAL MODULATOR



24.0 CAPTURE/COMPARE/PWM MODULES

The Capture/Compare/PWM module is a peripheral which allows the user to time and control different events, and to generate Pulse-Width Modulation (PWM) signals. In Capture mode, the peripheral allows the timing of the duration of an event. The Compare mode allows the user to trigger an external event when a predetermined amount of time has expired. The PWM mode can generate Pulse-Width Modulated signals of varying frequency and duty cycle.

This family of devices contains two Enhanced Capture/Compare/PWM modules (ECCP1 and ECCP2) and two standard Capture/Compare/PWM modules (CCP3 and CCP4).

The capture and compare functions are identical for all four CCP modules (ECCP1, ECCP2, CCP3, and CCP4). The only differences between CCP modules are in the Pulse-Width Modulation (PWM) function. The standard PWM function is identical in modules, CCP3 and CCP4. In CCP modules ECCP1 and ECCP2, the Enhanced PWM function has slight variations from one another. Full-Bridge ECCP modules have four available I/O pins while Half-Bridge ECCP modules only have two available I/O pins. See Table 24-1 for more information.

Note 1: In devices with more than one CCP module, it is very important to pay close attention to the register names used. A number placed after the module acronym is used to distinguish between separate modules. For example, the CCP1CON and CCP2CON control the same operational aspects of two completely different CCP modules.

2: Throughout this section, generic references to a CCP module in any of its operating modes may be interpreted as being equally applicable to ECCP1, ECCP2, CCP3 and CCP4. Register names, module signals, I/O pins, and bit names may use the generic designator ‘x’ to indicate the use of a numeral to distinguish a particular module, when required.

TABLE 24-1: PWM RESOURCES

Device Name	ECCP1	ECCP2	CCP3	CCP4
PIC16(L)F1824/8	Enhanced PWM Full-Bridge	Enhanced PWM Half-Bridge	Standard PWM	Standard PWM

FIGURE 25-3: MSSP1 BLOCK DIAGRAM (I^2C™ SLAVE MODE)

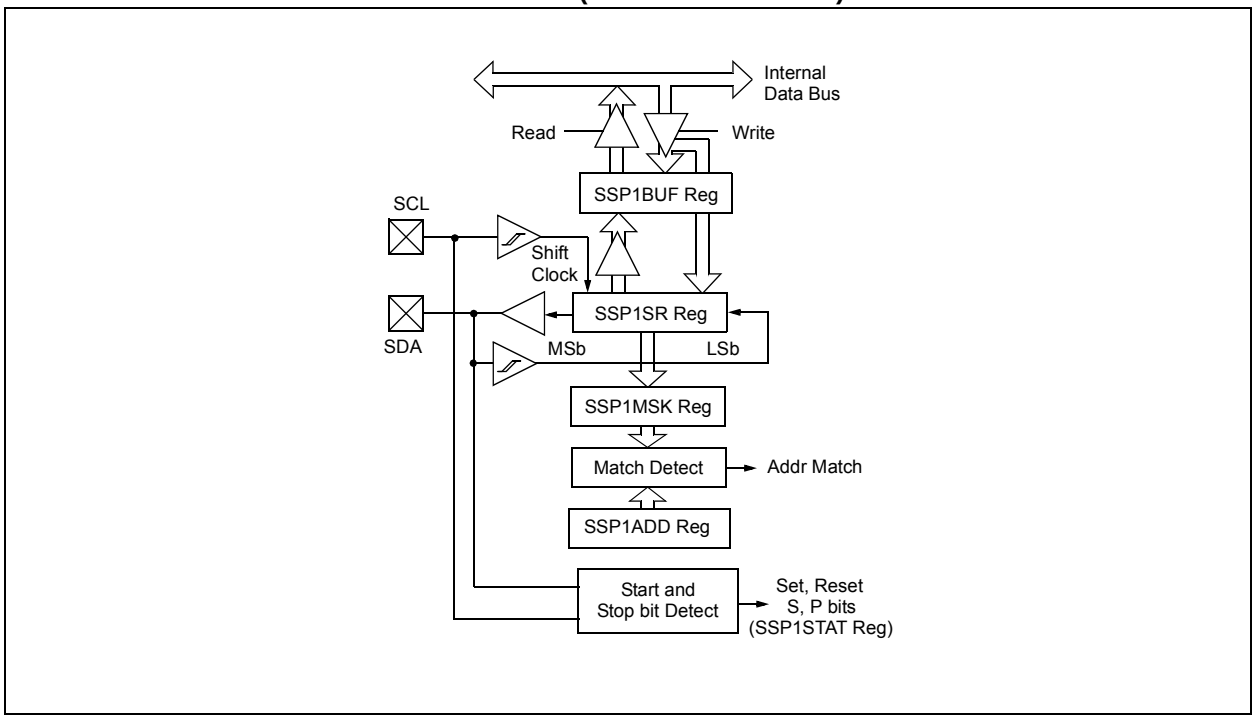
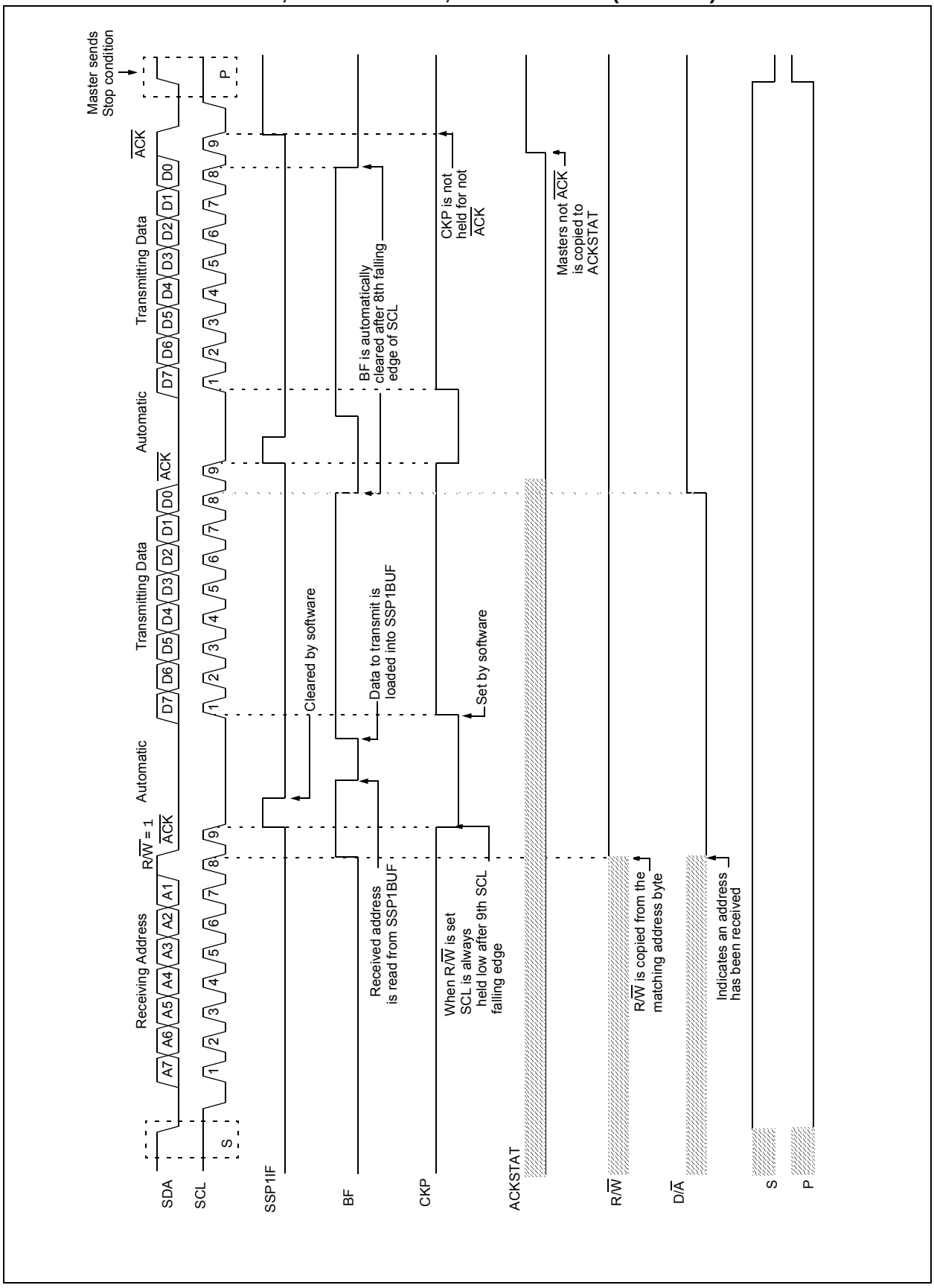


FIGURE 25-18: I²C SLAVE, 7-BIT ADDRESS, TRANSMISSION (AHEN = 0)



25.5.4 SLAVE MODE 10-BIT ADDRESS RECEPTION

This section describes a standard sequence of events for the MSSP1 module configured as an I^2C Slave in 10-bit Addressing mode.

Figure 25-20 is used as a visual reference for this description.

This is a step by step process of what must be done by slave software to accomplish I^2C communication.

1. Bus starts Idle.
2. Master sends Start condition; S bit of SSP1STAT is set; SSP1IF is set if interrupt on Start detect is enabled.
3. Master sends matching high address with R/$\overline{W}$ bit clear; UA bit of the SSP1STAT register is set.
4. Slave sends $\overline{ACK}$ and SSP1IF is set.
5. Software clears the SSP1IF bit.
6. Software reads received address from SSP1BUF clearing the BF flag.
7. Slave loads low address into SSP1ADD, releasing SCL.
8. Master sends matching low address byte to the Slave; UA bit is set.

Note:	Updates to the SSP1ADD register are not allowed until after the $\overline{ACK}$ sequence.

9. Slave sends $\overline{ACK}$ and SSP1IF is set.

Note:	If the low address does not match, SSP1IF and UA are still set so that the slave software can set SSP1ADD back to the high address. BF is not set because there is no match. CKP is unaffected.

10. Slave clears SSP1IF.
11. Slave reads the received matching address from SSP1BUF clearing BF.
12. Slave loads high address into SSP1ADD.
13. Master clocks a data byte to the slave and clocks out the slaves $\overline{ACK}$ on the ninth SCL pulse; SSP1IF is set.
14. If SEN bit of SSP1CON2 is set, CKP is cleared by hardware and the clock is stretched.
15. Slave clears SSP1IF.
16. Slave reads the received byte from SSP1BUF clearing BF.
17. If SEN is set the slave sets CKP to release the SCL.
18. Steps 13-17 repeat for each received byte.
19. Master sends Stop to end the transmission.

25.5.5 10-BIT ADDRESSING WITH ADDRESS OR DATA HOLD

Reception using 10-bit addressing with AHEN or DHEN set is the same as with 7-bit modes. The only difference is the need to update the SSP1ADD register using the UA bit. All functionality, specifically when the CKP bit is cleared and SCL line is held low are the same. Figure 25-21 can be used as a reference of a slave in 10-bit addressing with AHEN set.

Figure 25-22 shows a standard waveform for a slave transmitter in 10-bit Addressing mode.

FIGURE 25-33: BUS COLLISION DURING START CONDITION (SDA ONLY)

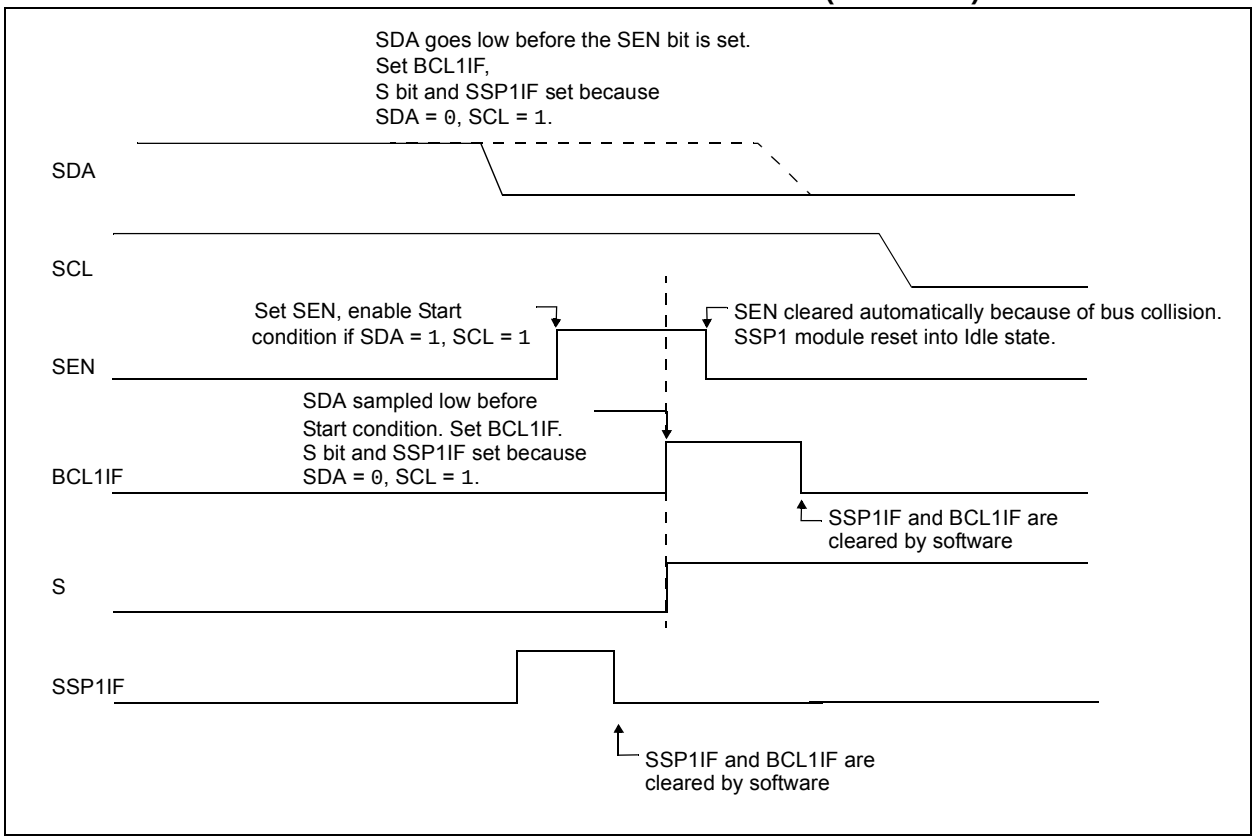
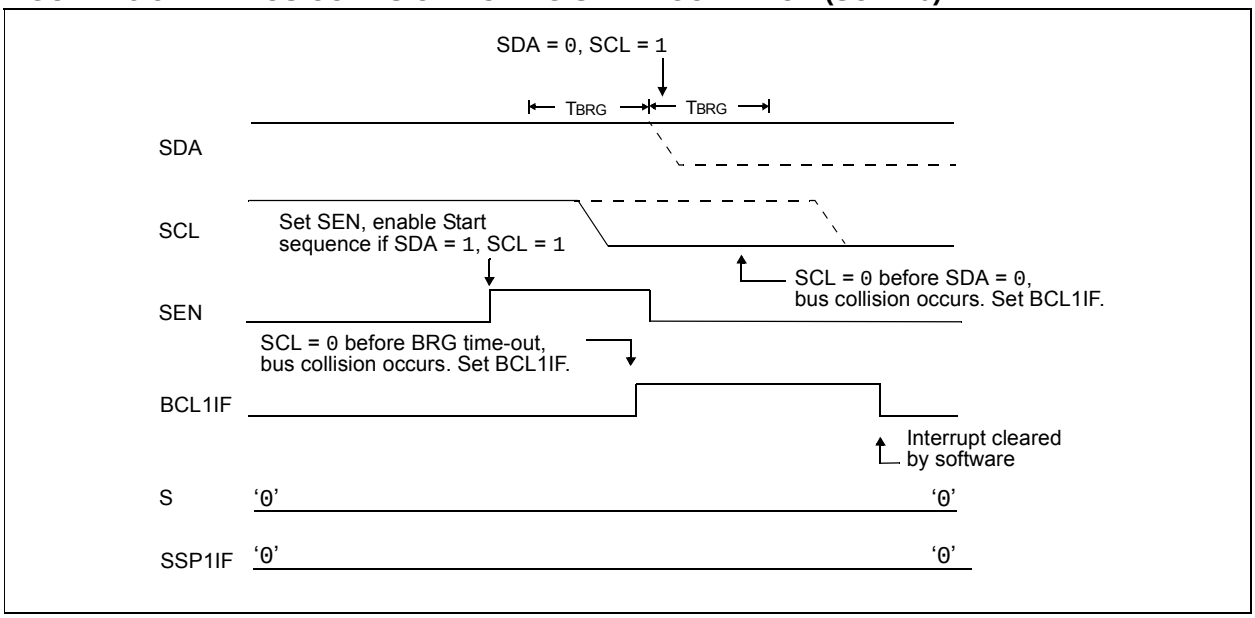


FIGURE 25-34: BUS COLLISION DURING START CONDITION (SCL = 0)



28.0 IN-CIRCUIT SERIAL PROGRAMMING™ (ICSP™)

ICSP™ programming allows customers to manufacture circuit boards with unprogrammed devices. Programming can be done after the assembly process allowing the device to be programmed with the most recent firmware or a custom firmware. Five pins are needed for ICSP™ programming:

- ICSPCLK
- ICSPDAT
- $\overline{MCLR}/V_{PP}$
- V_{DD}
- V_{SS}

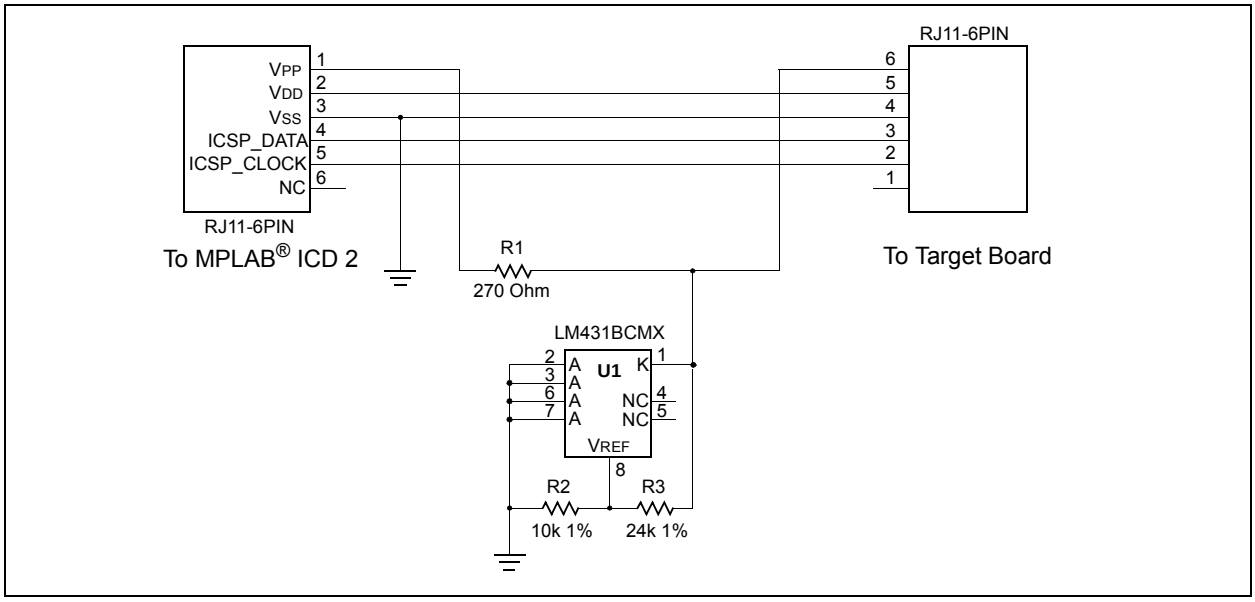
In Program/Verify mode the Program Memory, User IDs and the Configuration Words are programmed through serial communications. The ICSPDAT pin is a bidirectional I/O used for transferring the serial data and the ICSPCLK pin is the clock input. For more information on ICSP™ refer to the "*PIC16F/LF182X/PIC12F/LF1822 Memory Programming Specification*" (DS41390).

28.1 High-Voltage Programming Entry Mode

The device is placed into High-Voltage Programming Entry mode by holding the ICSPCLK and ICSPDAT pins low then raising the voltage on $\overline{MCLR}/V_{PP}$ to V_{IHH}.

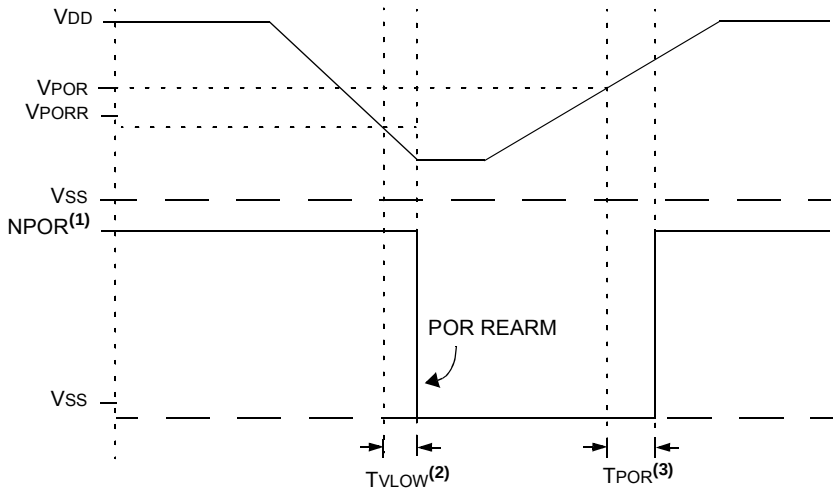
Some programmers produce V_{PP} greater than V_{IHH} (9.0V), an external circuit is required to limit the V_{PP} voltage. See Figure 28-1 for example circuit.

FIGURE 28-1: VPP LIMITER EXAMPLE CIRCUIT



Note:	The MPLAB ICD 2 produces a V_{PP} voltage greater than the maximum V_{PP} specification of the PIC16(L)F1824/8.

FIGURE 30-4: POR AND POR REARM WITH SLOW RISING VDD



Note 1: When NPOR is low, the device is held in Reset.
2: TPOR 1 μs typical.
3: TVLOW 2.7 μs typical.

TABLE 30-14: SPI MODE REQUIREMENTS

Param No.	Symbol	Characteristic		Min.	Typ†	Max.	Units	Conditions
SP70*	TssL2scH, TssL2scL	$\overline{SSx}\downarrow$ to SCKx$\downarrow$ or SCKx$\uparrow$ input		2.25 Tcy	—	—	ns	
SP71*	TscH	SCKx input high time (Slave mode)		Tcy + 20	—	—	ns	
SP72*	TscL	SCKx input low time (Slave mode)		Tcy + 20	—	—	ns	
SP73*	TdiV2scH, TdiV2scL	Setup time of SDIx data input to SCKx edge		100	—	—	ns	
SP74*	TscH2diL, TscL2diL	Hold time of SDIx data input to SCKx edge		100	—	—	ns	
SP75*	TdoR	SDO data output rise time	3.0-5.5V	—	10	25	ns	
			1.8-5.5V	—	25	50	ns	
SP76*	TdoF	SDOx data output fall time		—	10	25	ns	
SP77*	TssH2doZ	$\overline{SSx}\uparrow$ to SDOx output high-impedance		10	—	50	ns	
SP78*	TscR	SCKx output rise time (Master mode)	3.0-5.5V	—	10	25	ns	
			1.8-5.5V	—	25	50	ns	
SP79*	TscF	SCKx output fall time (Master mode)		—	10	25	ns	
SP80*	TscH2doV, TscL2doV	SDOx data output valid after SCKx edge	3.0-5.5V	—	—	50	ns	
			1.8-5.5V	—	—	145	ns	
SP81*	TdoV2scH, TdoV2scL	SDOx data output setup to SCKx edge		Tcy	—	—	ns	
SP82*	TssL2doV	SDOx data output valid after $\overline{SS}\downarrow$ edge		—	—	50	ns	
SP83*	TscH2ssH, TscL2ssH	$\overline{SSx}\uparrow$ after SCKx edge		1.5Tcy + 40	—	—	ns	

* These parameters are characterized but not tested.

† Data in “Typ” column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 31-39: IPD, COMPARATOR, NORMAL-POWER MODE (CxSP = 1), PIC16LF1824/8 ONLY

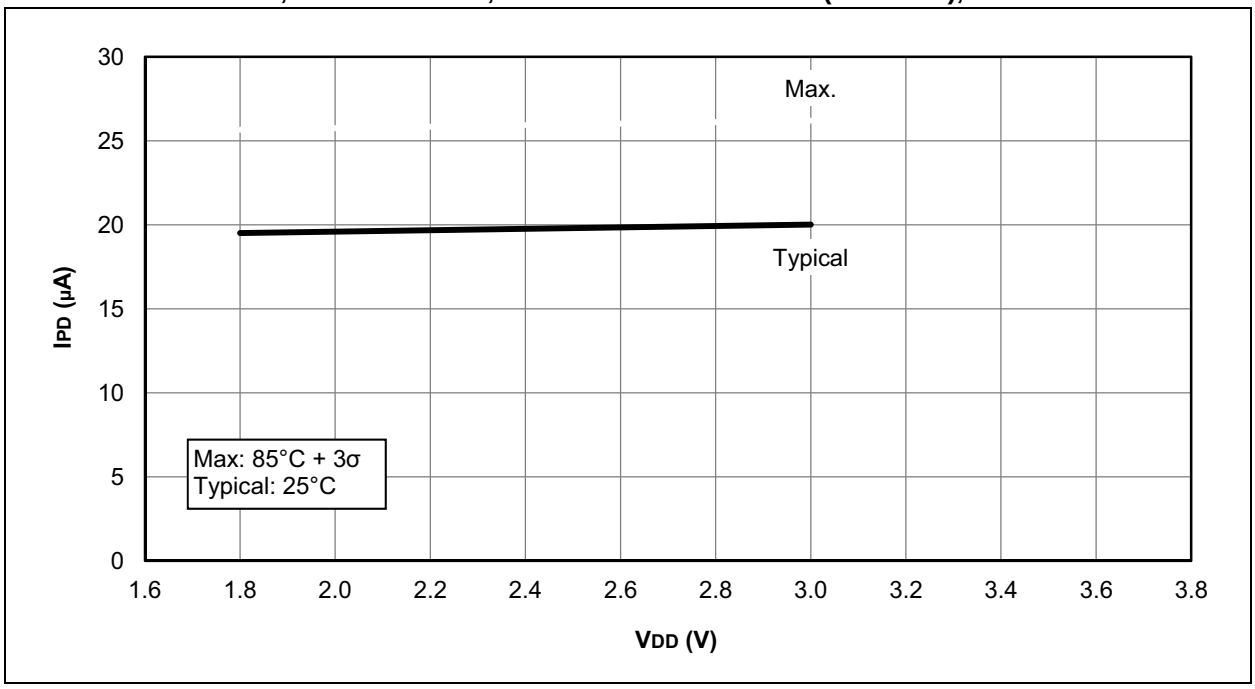
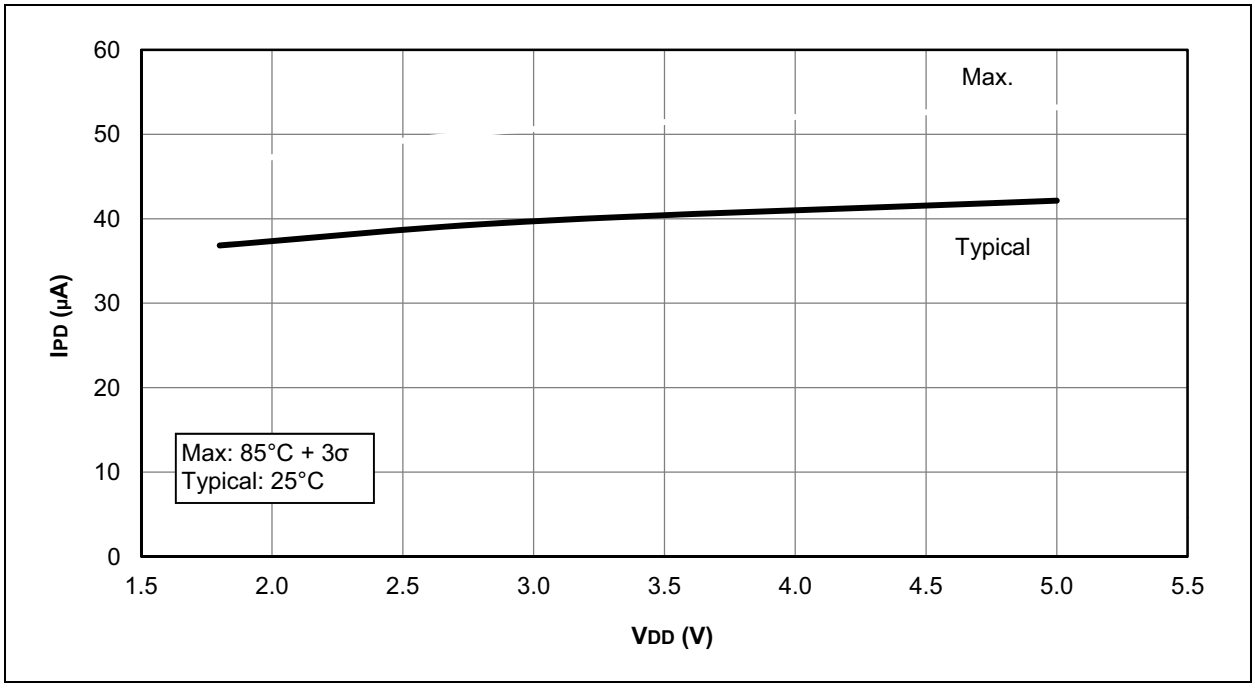
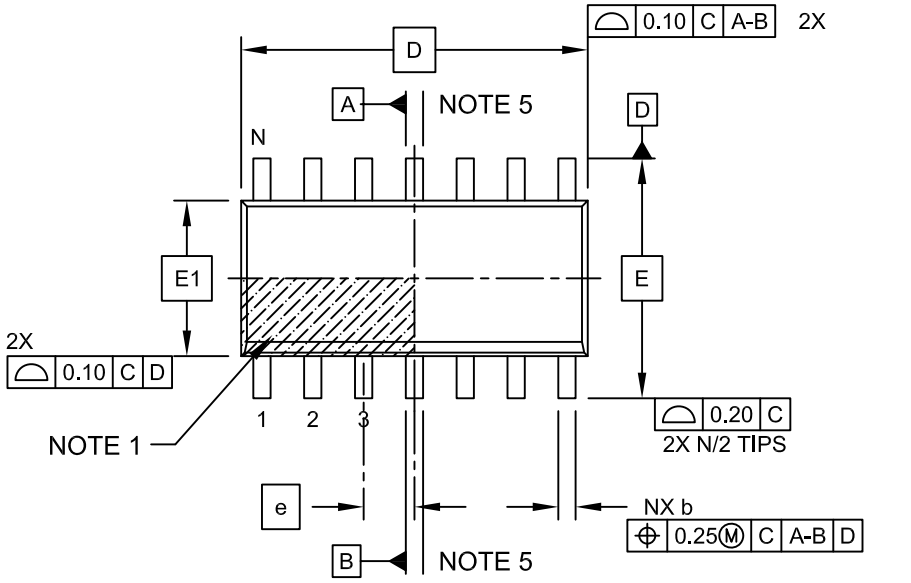


FIGURE 31-40: IPD, COMPARATOR, NORMAL-POWER MODE (CxSP = 1), PIC16F1824/8 ONLY

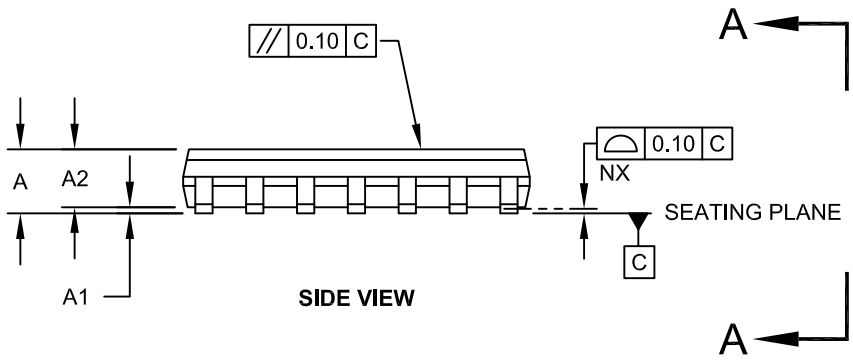


14-Lead Plastic Small Outline (SL) - Narrow, 3.90 mm Body [SOIC]

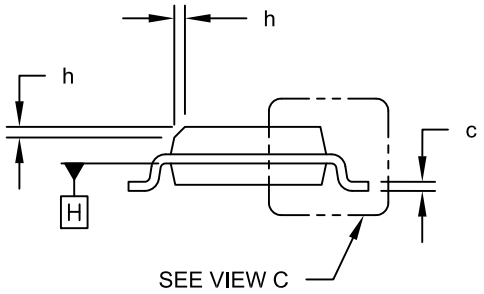
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



TOP VIEW



SIDE VIEW



VIEW A-A

Microchip Technology Drawing No. C04-065C Sheet 1 of 2